



PK582 (v1.0) September 21,  
2012

## 100% Material Declaration Data Sheet FGG400 XC3S400AN

**Average Weight: 2.0000 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die (FPGA)</b>					<b>0.017871</b>	<b>0.894</b>
	Silicon (Si)	7440-21-3	100.00		0.017871	
<b>Silicon Die (PROM)</b>					<b>0.002099</b>	<b>0.105</b>
	Silicon (Si)	7440-21-3	100.00		0.002099	
<b>Die attach</b>					<b>0.002719</b>	<b>0.136</b>
	Silver	7440-22-4	77.50		0.002107	
	Bismaleimide Monomer	Trade Secret	15.00		0.000408	
	Acrylate Monomer	Trade Secret	7.50		0.000204	
<b>Film</b>					<b>0.000220</b>	<b>0.011</b>
	Epoxy Resin	N/A	12.50		0.000028	
	Phenol Resin	N/A	12.50		0.000028	
	Amorphous Silica	7631-86-9	35.00		0.000077	
	Synthetic Rubber	N/A	40.00		0.000088	
<b>Mold Compound</b>					<b>0.824233</b>	<b>41.212</b>
	Silica Fused	60676-86-0	70.90		0.584381	
	Silica Fused	7631-86-9	15.00		0.123635	
	Silica, Crystalline	14808-60-7	0.30		0.002473	
	Epoxy resin A	Trade Secret	3.00		0.024727	
	Epoxy resin B	Trade Secret	3.00		0.024727	
	Phenol resin A	Trade Secret	3.00		0.024727	
	Phenol resin B	Trade Secret	3.00		0.024727	
	Metal Hydroxide	Trade Secret	1.50		0.012363	
	Carbon Black	1333-86-4	0.30		0.002473	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Gold Wire 1</b>					<b>0.016172</b>	<b>0.809</b>
	Gold	7440-57-5	99.05		0.016018	
	Palladium	7440-05-3	0.95		0.000154	
	Calcium	7440-70-2	0.00		0.000000	
<b>Gold Wire 2</b>					<b>0.000546</b>	<b>0.027</b>
	Gold	7440-57-5	99.05		0.000541	
	Palladium	7440-05-3	0.95		0.000005	
	Calcium	7440-70-2	0.00		0.000000	
<b>Solder Ball</b>					<b>0.335050</b>	<b>16.753</b>
	Tin	7440-31-5	95.50		0.319973	
	Silver	7440-22-4	4.00		0.013402	
	Copper	7440-50-8	0.50		0.001675	
<b>Substrate</b>					<b>0.801090</b>	<b>40.055</b>
	Copper	7440-50-8	35.78		0.286630	
	Nickel	7440-02-0	3.98		0.031883	
	Gold	7440-57-5	0.48		0.003845	
	Glass fiber	65997-17-3	16.69		0.133702	
	Halogen FR	N/A	0.10		0.000801	
	BT Core	13676-54-5 25722-66-1 29690-82-2 26265-08-7 13776-74-4 7631-86-9 7440-50-8	34.25		0.274373	
	Solder mask	64742-94-5 14807-96-6 7727-43-7 7631-86-9 34590-94-8	8.72		0.069855	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/21/12	1.0	Initial Xilinx release.

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